

Hennigsdorf, 29.04.2025

Tresky Automation presents contract manufacturing service for packaging at PCIM 2025

Tresky Automation is excited to introduce its new contract manufacturing service for packaging at PCIM 2025. This innovative service offers customized solutions for various fields, including photonics, optoelectronics, sintering for power electronics, flip chip bonding, and many other assembly and connection technologies.

The demand for contract manufacturing capabilities for prototypes and small to medium-sized series in the field of assembly and connection technology remains high. Tresky Automation's customers benefit not only from extensive DIE bonding processes and in-depth expertise, but also from a broad portfolio of DIE bonding equipment.

"Many companies are reluctant to invest directly in their own equipment, especially during the prototype development phase and for small series. Product or manufacturing process adjustments are often necessary before the final design is finalized," explains Daniel Schultze, Managing Director of Tresky GmbH. "At the same time, there is a desire to have prototypes and small quantities produced quickly and in high quality. This is exactly where we come in."

With comprehensive technical expertise and many years of experience, the Tresky team takes care of prototype and small-batch production in its in-house laboratory, right from the very first component. "In our contract manufacturing hub, we offer a wide range of highly specialized packaging and assembly processes for the precise and reliable processing of semiconductor chips," Schultze continues.

Tresky's state-of-the-art facilities and technologies enable the development of tailor-made solutions that meet specific customer requirements. The use of innovative processes not only increases efficiency but also maximizes the quality of the packages. "Our tailored solutions enable projects to be implemented quickly and efficiently, significantly reducing development times and time-to-market," says Schultze.

Tresky's experienced team provides customers with expert advice. As an external partner, Tresky manufactures small series quickly and in line with requirements, without customers having to build up their own production capacities. "We help to reduce production costs and times without compromising on quality," adds Schultze.

Tresky Automation will present its DIE bonding and service solutions at the PCIM Expo in Nuremberg from May 6 to 8, 2025, in **Hall 5, Booth 335**.

About Tresky

Since 2013, the name TRESKY Automation has stood for the highest quality, flexibility and maximum reliability. As one of the world's leading machine manufacturers for placement systems in the high-precision sector, Tresky GmbH specializes in the development and production of innovative bonding solutions.

The philosophy of Tresky Automation is based on the principle of quality "Made in Germany". This means that all development, production and sales processes take place at the headquarters. Tresky GmbH is based in Hennigsdorf, a town close to the capital Berlin. This location is not only strategically favorable, but also of great importance, as it is

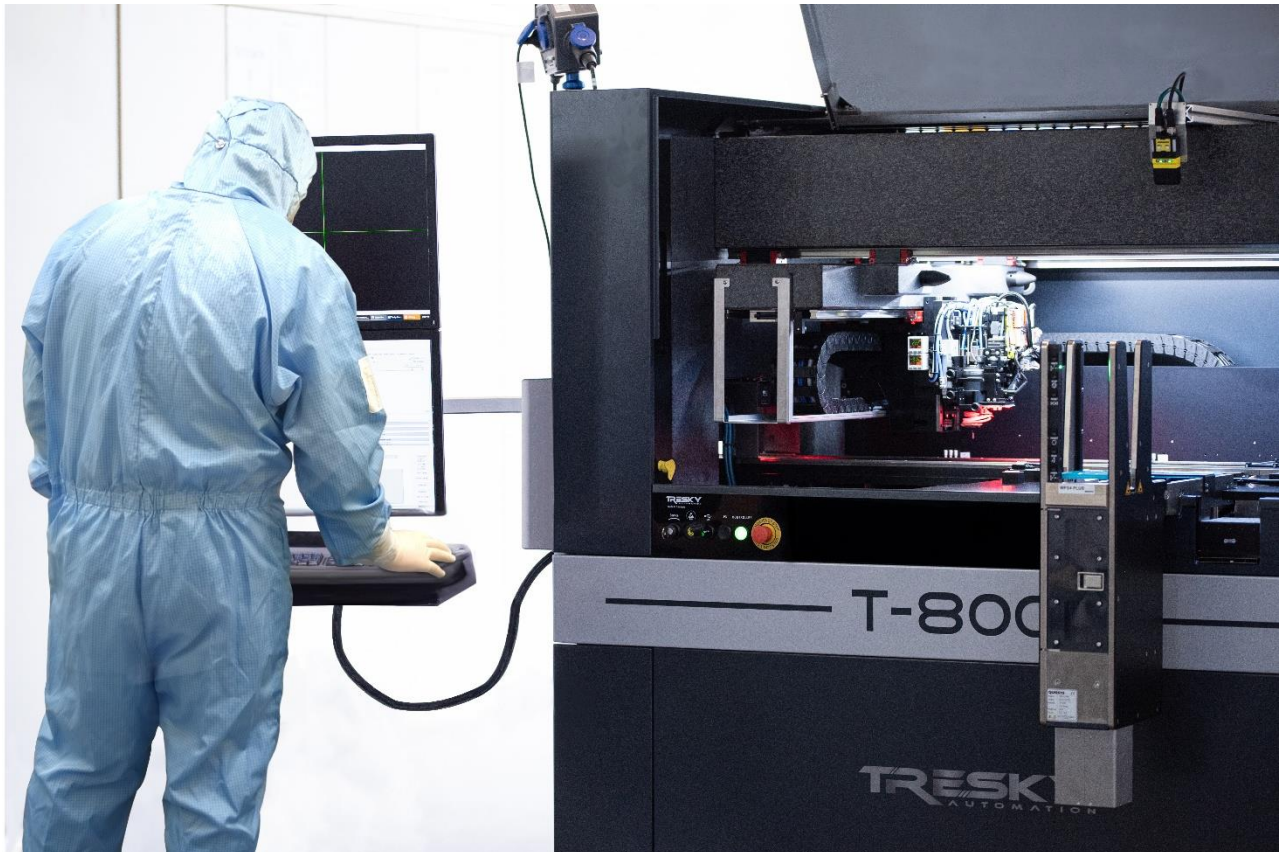
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home to numerous highly specialized companies from the automation, electrical and communication technology and life science sectors.

Further information can be found at: [Tresky - DIE Bonder for R&D and Production](#)

Picture:



Picture caption:

Tresky Automation expands its machine park for contract manufacturing

Deeplinks:

[DIE bonding prototyping and the production of small series](#)

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